

PG300WT Wafer Thickness Metrology

PG300WT is a new design wafer thickness metrology by Pegasus Inc. for semiconductor material. PG300WT use high accuracy and fast non contact capacitive sensors to measure wafer thickness, and it's easy to use touch panel to control and set measurement mode. PG300WT is capable of measuring wafer thickness, total thickness variation (TTV) etc. measurement mode.

Features:

- Control by Touch panel and display result on the screen
- Table top design, easy to use
- 5-point and TTV measurements
- Supported material surface: As-Cut, Lapped,
- Etched, Polished, Patterned wafer
- Non clean room environment

Main Material:

- Si
- SiC
- Ge
- InP
- GaAs
- GaN

Specifications

- | | |
|------------------------------------|---------------------------------------|
| • Thickness range: 300um to 1050um | • Sample Size: 75mm to 300mm |
| • Accuracy: $\pm 0.5\mu\text{m}$ | • Repeatability: $\pm 0.5\mu\text{m}$ |
| • Resolution: 0.1um | • Probe diameter: 5mm |
| • Operate method: Touch Panel | • Dimension: 389mm*374mm*365mm |

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